BGA Adapter System Part I
Solder Adapter

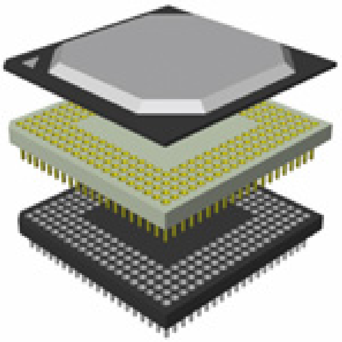
RoHS 2002/95/EC compliant

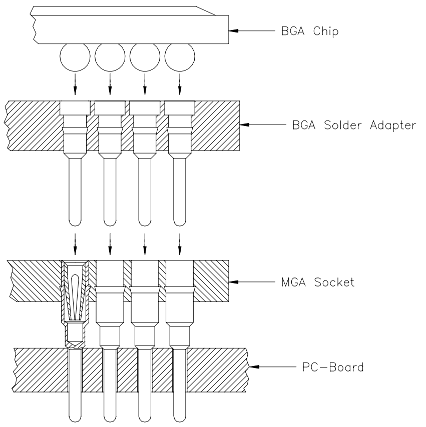
E-tec Interconnect

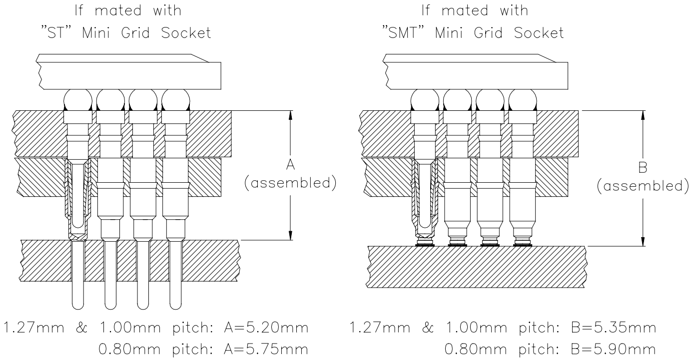
The E-tec BGA Adapter System comprises two elements, the BGA solder adapter onto which the BGA chip is soldered (converting the BGA chip to a PGA), and the Mini Grid Socket which is soldered to the PCB. The solder adapter can then be plugged into the Mini Grid Socket (page 16).

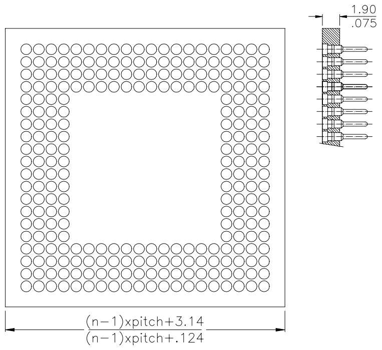
E-tec offers any pin-out, configuration and grid size.

Special terminal designs are possible on request.

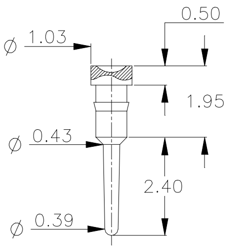




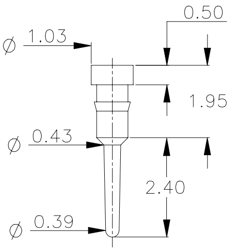




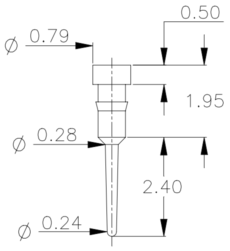
Terminal styles



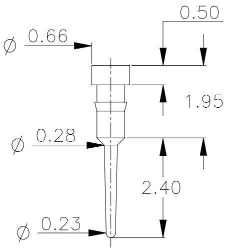
Type **116**
Standard *for 1,27mm pitch*



Type **158**
Optional for 1,27mm pitch



Type **168**
if 1,00mm pitch



Type **175**
if 0,80mm pitch

Specifications

Terminal	**Material**	**Plating**	**Adapter**	**Others**
Type 116, 158 & 168	CuZn	Au over Ni over Cu	Material : FR 4 glass Epoxy UL 94V-0	Operating Temperature : –55°C to +125°C ; 260°C for 60 sec.

How to order

BGA Solder Adapter ABG xxxx - E xxx - xx X 55 xx

Nbr of contacts / balls
as per device

Terminal style
Please refer to the drawings shown above

Grid size / **Config Code**
will be given by the factory after receipt of the chip datasheet

Plating
55 = gold

Pitch of Grid Array
08 = 0.80mm
10 = 1.00mm
12 = 1.27mm
15 = 1.50mm
others on request